

L Number	Hits	Search Text	DB	Time stamp
1	61	plug\$4 with (hole via spac\$3 open\$4) and ((circuit adj pattern) trace) and ((doctor with blad\$3) squeegee) and (resist dielectric insulat\$3)	USPAT; EPO; JPO	2004/02/20 10:07
2	6	plug\$4 with (hole via spac\$3 open\$4) same ((circuit adj pattern) (conductive adj trace)) same (resist dielectric insulat\$3) and ((doctor with blad\$3) squeegee)	USPAT; EPO; JPO	2004/02/20 10:10
3	65	plug\$4 with (hole via spac\$3 open\$4) same (resist dielectric insulat\$3) and ((doctor with blad\$3) squeegee)	USPAT; EPO; JPO	2004/02/20 10:21
4	789	(fill\$3 plug\$4) with (hole via spac\$3 open\$4) same (solder adj resist insulating adj resin)	USPAT; EPO; JPO	2004/02/20 10:22
5	29	((fill\$3 plug\$4) with (hole via spac\$3 open\$4) same (solder adj resist insulating adj resin)) and ((doctor with blad\$3) squeegee)	USPAT; EPO; JPO	2004/02/20 10:38
7	997	29/\$.ccls. and ((doctor with blad\$3) squeegee)	USPAT; EPO; JPO	2004/02/20 10:38
8	48	29/\$.ccls. and ((doctor with blad\$3) squeegee) and (solder adj resist insulating adj resin)	USPAT; EPO; JPO	2004/02/20 12:03
9	44	427/\$.ccls. and ((doctor with blad\$3) squeegee) and (solder adj resist insulating adj resin)	USPAT; EPO; JPO	2004/02/20 12:21
10	0	63318798.URPN.	USPAT	2004/02/20 12:21
11	8	427/\$.ccls. and ((doctor with blad\$3) squeegee) and (hole spac\$3 via open\$4) with solder adj resist	USPAT; EPO; JPO	2004/02/20 12:22
12	8	((doctor with blad\$3) squeegee) and (plug\$4 fill\$3) with (hole spac\$3 via open\$4) with solder adj resist	USPAT; EPO; JPO	2004/02/20 12:24
13	24	((doctor with blad\$3) squeegee) same (hole spac\$3 via open\$4) with solder adj resist	USPAT; EPO; JPO	2004/02/20 12:27
14	618	((doctor with blad\$3) squeegee) same (hole via) with (plug\$4 fill\$3)	USPAT; EPO; JPO	2004/02/20 12:28
15	4	((doctor with blad\$3) squeegee) same (hole via) with (plug\$4 fill\$3) with solder adj resist	USPAT; EPO; JPO	2004/02/20 12:29
16	0	((doctor with blad\$3) squeegee) same (hole via) with (plug\$4 fill\$3) with insulating adj resin	USPAT; EPO; JPO	2004/02/20 12:30
17	23	((doctor with blad\$3) squeegee) same (hole via) with (plug\$4 fill\$3) with insulating	USPAT; EPO; JPO	2004/02/20 15:19
18	18	4715117.URPN.	USPAT	2004/02/20 12:32
19	27	4792646.URPN.	USPAT	2004/02/20 12:34
20	37	("3613230" "4017968" "4319708" "4681649" "4704791" "4791248" "4792646" "4967314" "4983252" "5006182" "5028743" "5117069" "5118458" "5146674" "5153986" "5224265" "5243142" "5271150" "5288665" "5346750" "5421083" "5443672" "5450290" "5451722" "5487218" "5557844" "5568682" "5571593" "5662987" "5665650" "5666722" "5685070" "5689091" "5740606" "5745984" "5779836" "5822856").PN.	USPAT	2004/02/20 12:39
34	158	((doctor with blad\$3) squeegee) same (hole via) and (no without) with (mask tencil)	USPAT; EPO; JPO	2004/02/20 15:21

35	10	((doctor with blad\$3) squeegee) same (hole via) and (no without) with (mask tencil)) and (fill\$3 plug\$4) with insulating	USPAT; EPO; JPO	2004/02/20 15:26
36	5	((doctor with blad\$3) squeegee) same (hole via) and (no without) with (mask tencil)) and (fill\$3 plug\$4) with resist	USPAT; EPO; JPO	2004/02/20 15:28
37	24	((doctor with blad\$3) squeegee) same (hole via) and (no without) with (mask tencil)) and (fill\$3 plug\$4) with resin	USPAT; EPO; JPO	2004/02/20 15:35
38	112	((doctor with blad\$3) squeegee) same (hole via) and (no without) with (mask tencil)) and (fill\$3 plug\$4)	USPAT; EPO; JPO	2004/02/20 16:18
39	1	4728568.pn.	USPAT; EPO; JPO	2004/02/20 16:18
40	12	4728568.URPN.	USPAT	2004/02/20 16:19
41	6	("3758433" "3948701" "4166150" "4255208" "4448622" "4503098").PN.	USPAT	2004/02/20 16:20
-	4	hole with plug\$4.ti. and Lee.in.	USPAT; EPO; JPO	2003/11/17 12:11
-	5	hole with plug\$4.ti. and Lee.in.	USPAT; US-PGPUB; EPO; JPO	2003/11/17 12:12
-	1	circuit adj board.ti. and air adj space and void adj formed	USPAT; EPO; JPO	2003/11/17 12:13
-	14	("4293377" "4360570" "5252195" "5284548" "5308929" "5309632" "5690837" "5863447" "6097089" "6228511" "6242078" "6282782" "6323436" "6376158").PN.	USPAT	2003/12/03 17:37
-	7	(hole via) with plug\$4 and ((solder adj resist) (insulating adj resin)) and squeegee	USPAT; EPO; JPO	2003/12/03 17:47
-	1	RE32430.URPN.	USPAT	2003/12/03 17:50
-	9	("3629036" "3824104" "3904492" "3984244" "4127436" "4230793" "4234626" "4260675" "4344998").PN.	USPAT	2003/12/03 17:50
-	21	4506004.URPN.	USPAT	2003/12/03 17:51
-	8	("3629036" "3824104" "3984244" "4127436" "4230793" "4234626" "4260675" "4344998").PN.	USPAT	2003/12/03 17:53
-	19	4804615.URPN.	USPAT	2003/12/03 17:53
-	22	5729437.URPN.	USPAT	2003/12/03 17:55
-	14	("4942364" "5446309" "5539241" "5742091" "5844299" "5877533" "5883335" "5898223" "5977845" "6002161" "6108212" "6180995" "6258688" "6287931").PN.	USPAT	2003/12/03 17:57
-	1	6631838.pn.	USPAT; EPO; JPO	2003/12/04 17:25
-	49	plug\$4 with hole and squeegee and mask\$3	USPAT; EPO; JPO	2003/12/04 17:27
-	49	4964948.URPN.	USPAT	2003/12/04 17:39
-	8	("3370351" "4521449" "4715117" "4817276" "4925723" "4964947" "4964948" "5120384").PN.	USPAT	2003/12/04 17:45
-	11	5274916.URPN.	USPAT	2003/12/04 17:46
-	43	(solder adj resist insulating adj resin) and (squeegee doctor adj blade) and circuit adj pattern and (hole via)	USPAT; EPO; JPO	2004/02/19 17:23
-	11	("4668532" "4786528" "5382333" "5439986" "5652042" "5670250" "5888627" "6060150" "6214455" "6355131" "6524717").PN.	USPAT	2004/02/19 12:29

-	2	("3948706" "4024629").PN.	USPAT	2004/02/19 14:16
-	50	4024629.URPN.	USPAT	2004/02/19 14:16
-	1	RE32430.URPN.	USPAT	2004/02/19 16:50
-	9	("3629036" "3824104" "3904492" "3984244" "4127436" "4230793" "4234626" "4260675" "4344998").PN.	USPAT	2004/02/19 16:50
-	1	6139904.pn.	USPAT; EPO; JPO	2004/02/19 16:53
-	5	("3158503" "4323593" "4401686" "4529477" "4763403").PN.	USPAT	2004/02/19 17:09
-	18	4529477.URPN.	USPAT	2004/02/19 17:10
-	18	4529477.URPN.	USPAT	2004/02/19 17:11
-	2	("4323593" "4324815").PN.	USPAT	2004/02/19 17:11
-	32	4323593.URPN.	USPAT	2004/02/19 17:11
-	5	("4323593" "4964948" "5191709" "5268194" "5822856").PN.	USPAT	2004/02/19 17:12
-	50	4964948.URPN.	USPAT	2004/02/19 17:14
-	11	((solder adj resist) (insulating adj resin)) same fill\$3 same (hole via) and (squeegee (doctor adj blad\$3)) and circuit adj pattern	USPAT; EPO; JPO	2004/02/19 17:28
-	29	((solder with resist) (insulating with resin)) same fill\$3 same (hole via open\$3 spac\$3) and (squeegee (doctor adj blad\$3)) and circuit adj pattern	USPAT; EPO; JPO	2004/02/19 17:32
-	583	29/846,852.ccls. and fill\$3 with (via hole open\$3 spac\$3)	USPAT; EPO; JPO	2004/02/19 17:36
-	60	(29/846,852.ccls. and fill\$3 with (via hole open\$3 spac\$3)) and solder with resist	USPAT; EPO; JPO	2004/02/19 17:34
-	88	29/846,852.ccls. and fill\$3 and (squeegee (doctor adj blad\$3))	USPAT; EPO; JPO	2004/02/19 17:37
-	4	("4323593" "5277761" "5323701" "5821179").PN.	USPAT	2004/02/19 17:38
-	4	("5659951" "5876842" "6175087" "6300575").PN.	USPAT	2004/02/19 17:40
-	7	("5014111" "5274916" "5384952" "5407864" "5615477" "5843251" "5848466").PN.	USPAT	2004/02/19 17:44
-	32	4323593.URPN.	USPAT	2004/02/19 18:01
-	9	5120384.URPN.	USPAT	2004/02/19 18:03
-	4	("3354542" "4336100" "4732636" "4902551").PN.	USPAT	2004/02/19 18:04
-	13	("4090231" "4109377" "4396936" "4919970" "5189261" "5427865" "5463191" "5492266" "5561322" "5593080" "5620129" "5759269" "5803340").PN.	USPAT	2004/02/19 18:05
-	15	("5041183" "5260170" "5286926" "5375042" "5378869" "5389742" "5466892" "5473120" "5495665" "5510216" "5576519" "5600103" "5744758" "5876842" "6010769").PN.	USPAT	2004/02/19 18:09
-	7	5268194.URPN.	USPAT	2004/02/19 18:12
-	6	("4145691" "4323593" "4324815" "4664945" "4938994" "5133120").PN.	USPAT	2004/02/19 18:12
-	50	4024629.URPN.	USPAT	2004/02/19 18:16
-	2	5087413.URPN.	USPAT	2004/02/19 18:23

-	8	("3852877" "4024629" "4434134" "4599277" "4671928" "4868034" "4954313" "4961879").PN.	USPAT	2004/02/19 18:23
-	16	4919970.URPN.	USPAT	2004/02/19 18:24
-	12	("3226255" "3735730" "4020206" "4023487" "4024629" "4127337" "4323593" "4459320" "4515304" "4529477" "4604966" "4761881").PN.	USPAT	2004/02/19 18:26
-	6	("3077511" "4024629" "4249302" "4604160" "4663497" "4792646").PN.	USPAT	2004/02/19 18:27
-	11	("2964007" "3516155" "4311267" "4323593" "4626309" "4694138" "4739919" "4774760" "4872261" "4953460" "5129573").PN.	USPAT	2004/02/19 18:37
-	25	5593080.URPN.	USPAT	2004/02/19 18:37

 Details
 Text
 Image
 HTML

US 5385868 A	19950131	Upward plug process for metal via holes	438/637	
US 4961390 A	19901009	Perforated plugs for air holes in a rotary combustor	110/246	
US 6372616 B1	20020416	Method of manufacturing an electrical interconnection of a semiconductor device using an erosion protection	438/592	Chao, Ying-Chen et al.
US 20020184757 A	20021212	Hole plugging method for printed circuit boards, and hole plugging device	29/852	Whitlow, Graham A. et al.
US 6631838 B2	20031014	Method for fabricating printed circuit board	228/225	Yoo, Bong-young et al.
US 6282782 B1	20010904	Forming plugs in vias of circuit board layers and subassemblies	29/852	Lee, Sung Gue et al.
US 6376158 B1	20020423	Methods for selectively filling apertures	430/315	Kim, Nam-Jin et al.
US RE32430 E	19870602	Printed wiring board	430/312	Biunno, Nicholas et al.
US 6504227 B1	20030107	Passive semiconductor device mounted as daughter chip on active semiconductor device	257/531	Jones, Gerald Walter et al.
US 4804615 A	19890214	Method for manufacture of printed circuit boards	430/314	Sullivan, Donald F.
US 5729437 A	19980317	Electronic part including a thin body of molding resin	361/760	Matsuo, Mie et al.
US 5665525 A	19970909	Method for producing printed circuit boards	430/315	Larson, Gary B. et al.
US 5324535 A	19940628	Process of coating printed wiring board with solid solder resist pattern formed from liquid and dry solder	427/76	Hashimoto, Nobuaki
US 6276055 B1	20010821	Method and apparatus for forming plugs in vias of a circuit board layer	29/852	Pienimaa, Seppo
US 6264862 B1	20010724	Method for manufacturing a plug	264/102	Ishido, Kiminori
US 4964948 A	19901023	Printed circuit board through hole technique	216/18	Bryan, Scott K. et al.
US 5229549 A	19930720	Ceramic circuit board and a method of manufacturing the ceramic circuit board	174/262	Liaw, Been-Yu
US 6139904 A	20001031	Method of making a printed board	427/97	Reed, Ronald G.
US 5274916 A	19940104	Method of manufacturing ceramic multilayer electronic component	29/848	Yamakawa, Akira et al.
US 4715117 A	19871229	Ceramic wiring board and its production	29/851	Yamasaki, Kozo et al.
US 6051093 A	20000418	Mounting method of semiconductor element	156/251	Kawabata, Shoichi et al.
US 6381838 B1	20020507	BGA package and method of manufacturing the same	29/848	Enomoto, Eyo
US 6329610 B1	20011211	Hybrid wiring board, semiconductor apparatus, flexible substrate, and fabrication method of hybrid wiring	174/264	Tsukahara, Norihito
US 5832600 A	19981110	Method of mounting electronic parts	29/841	Ahn, Eun Chul et al.
US 5662987 A	19970902	Multilayer printed wiring board and method of making same	428/209	Takubo, Chiaki et al.
US 5304392 A	19940419	Method of manufacturing printed wiring board	427/96	Hashimoto, Nobuaki
US 5268194 A	19931207	Method of packing filler into through-holes in a printed circuit board	427/97	Mizumoto, Shogo et al.
US 5145691 A	19920908	Apparatus for packing filler into through-holes or the like in a printed circuit board	425/110	Matsumoto, Masuo
US 5090120 A	19920225	Process for forming solder lands in a printed wiring board manufacturing method	29/846	Kawakami, Shin et al.
US 4323593 A	19820406	Method of printing a spot pattern in a printed circuit board	427/97	Kawakami, Shin et al.
US 4024629 A	19770524	Fabrication techniques for multilayer ceramic modules	29/852	Matsumoto, Masuo
US 5087413 A	19920211	Conducting material and a method of fabricating thereof	419/9	Tsunashima, Eiichi
US 4919970 A	19900424	Solder deposition control	427/96	Lemonie, Jean Marie et al.
US 4908940 A	19900320	Method of manufacturing two-layer printed circuit sheet	29/852	Abe, Kenichiro
US 4383495 A	19830517	Apparatus for coating surfaces of a substrate	118/406	Hoebener, Karl G. et al.
US 6060150 A	20000509	Sheet for a thermal conductive substrate, a method for manufacturing the same, a thermal conductive substrate	428/209	Amano, Toshiaki et al.
US 5120384 A	19920609	Method of manufacturing multilayer laminate	156/242	Plichta, George J. et al.